

In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

Listing of Claims

1. (Original) A bonding pad structure, comprising:
a bonding pad substantially surrounded and insulated by a dielectric layer, wherein the bonding pad comprises at least one first conductive layer having a wiring layer with a stripe layout and a first edge portion, a second conductive layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and
a conductive structure connecting the first edge portion and the second edge portion.
2. (Original) The structure according to claim 1, further comprising:
an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.
3. (Original) The structure according to claim 1, wherein a material of the dielectric layer is a low dielectric constant material.
4. (Original) The structure according to claim 1, wherein the first conductive layer is a metal layer.

5. (Original) The structure according to claim 1, wherein the second conductive layer is a metal layer.

6. (Original) The structure according to claim 1, wherein the conductive structure is an array of metal plugs.

7. (Original) The structure according to claim 1, wherein the conductive structure is a metal damascene structure.

8. (Original) A bonding pad structure, comprising:
a substrate having an interlevel dielectric (ILD) layer thereon,
a bonding pad formed on the ILD layer and substantially surrounded and insulated by an intermetal dielectric (IMD) layer, wherein the bonding pad comprises at least one metal layer having a wiring layer with a stripe layout and a first edge portion, a bonding metal layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and
a conductive structure connecting the first edge portion and the second edge portion.

9. (Original) The structure according to claim 8, further comprising:
an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.

10. (Original) The structure according to claim 8, wherein a material of the IMD layer is a low dielectric constant material.

11. (Original) The structure according to claim 8, wherein the conductive structure is an array of metal plugs.

12. (Original) The structure according to claim 8, wherein the conductive structure is a metal damascene structure.

13. – 23. Canceled.